



# ALD of Manganese Silicate

## Citation

Gordon, Roy G., Lu Sun, Qiang Chen, Jin-Seong Park, Sang Bok Kim. 2015. ALD of Manganese Silicate. In Proceedings of the AVS Atomic Layer Deposition Conference, Portland, Oregon, June 28 - July 1.

## Permanent link

<http://nrs.harvard.edu/urn-3:HUL.InstRepos:34325478>

## Terms of Use

This article was downloaded from Harvard University's DASH repository, and is made available under the terms and conditions applicable to Open Access Policy Articles, as set forth at <http://nrs.harvard.edu/urn-3:HUL.InstRepos:dash.current.terms-of-use#OAP>

## Share Your Story

The Harvard community has made this article openly available.  
Please share how this access benefits you. [Submit a story](#).

[Accessibility](#)

# ALD of Manganese Silicate

Roy G. Gordon,<sup>1,2\*</sup> Lu Sun,<sup>2</sup> Qiang Chen,<sup>3</sup> Jin-Seong Park<sup>4</sup>  
and Sang Bok Kim<sup>1</sup>

<sup>1</sup>Department of Chemistry and Chemical Biology

<sup>2</sup>School of Engineering and Applied Sciences

Harvard University, Cambridge, MA, USA

<sup>3</sup>Beijing Institute of Graphic Communication, Beijing, China

<sup>4</sup>Hanyang University, Seoul, Korea

\*Email: [gordon@chemistry.harvard.edu](mailto:gordon@chemistry.harvard.edu)



# Outline

**Potential Applications of Manganese Silicate**

**ALD Process for Manganese Oxide, MnO**

**ALD Process for Manganese Silicate**

**Properties of Manganese Silicate**

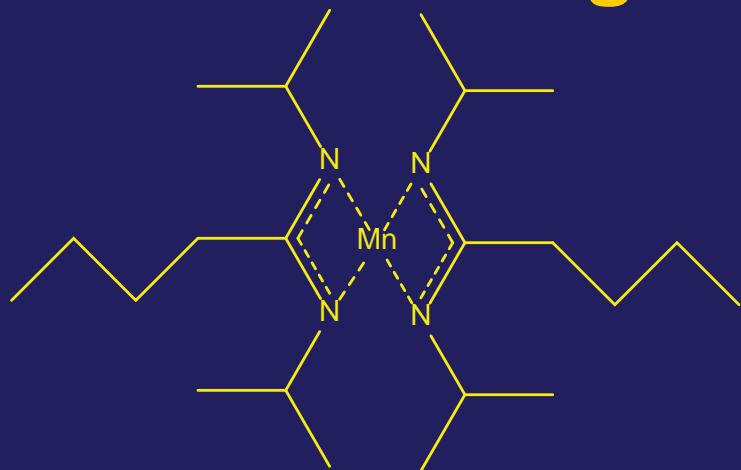


# Potential Applications of $\text{MnSi}_x\text{O}_y$

Copper wires in computer chips could use  $\text{MnSi}_x\text{O}_y$  as a

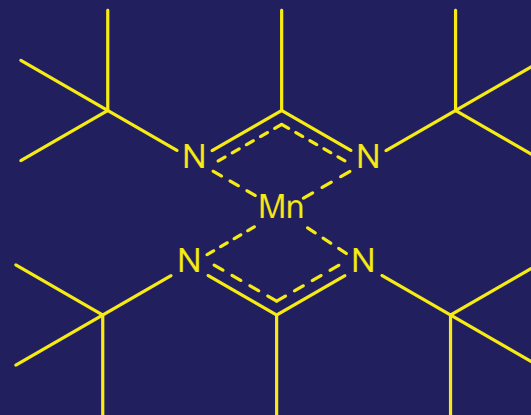
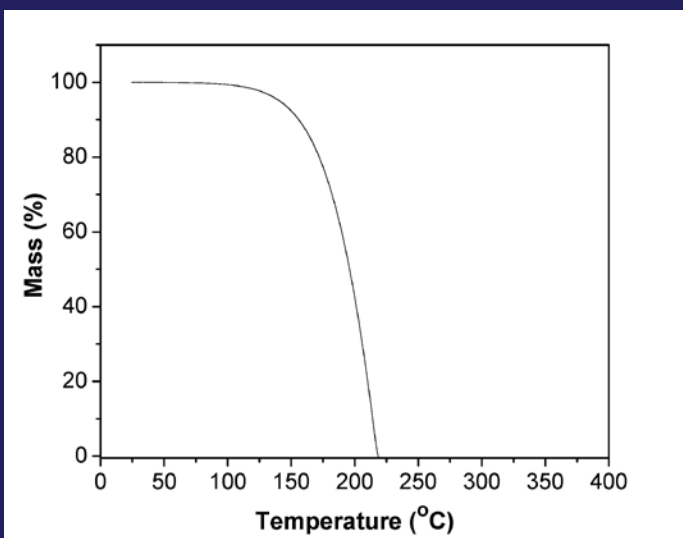
- barrier to diffusion of copper, water and oxygen
- adhesion promoter between copper and insulators
- nucleating layer for vapor deposition of copper

# Manganese Precursors



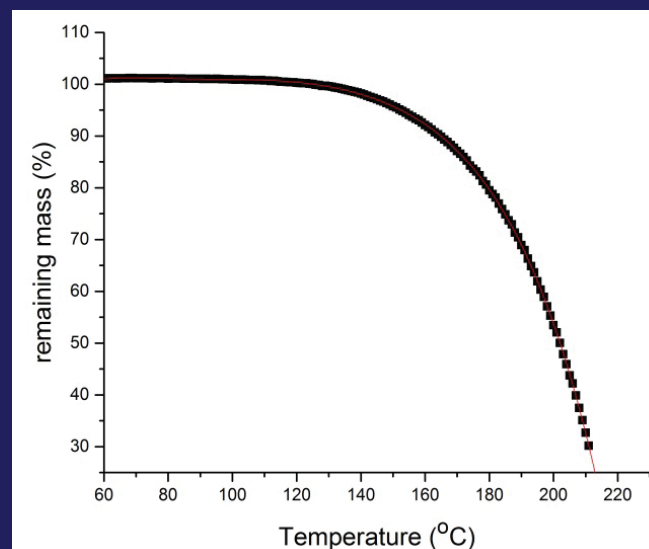
manganese(II)  
bis(*N,N'*-diisopropylpentamidine)

melting point: 60 °C  
boiling point: 120 °C / 0.02 torr



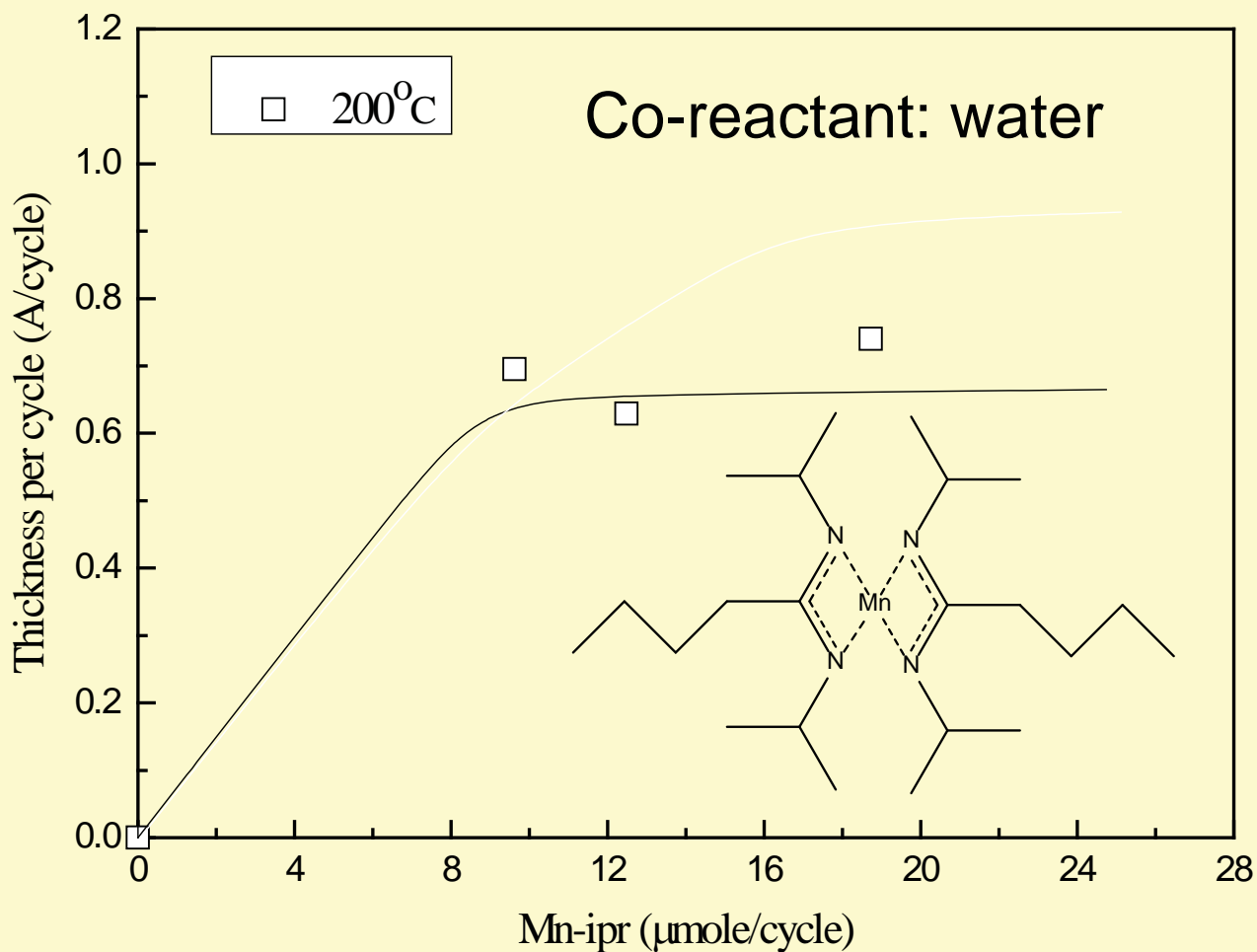
manganese(II)  
bis(*N,N'*-di-*tert*-butylacetamidine)

melting point: 107 °C  
boiling point: 100 °C / 0.07 torr



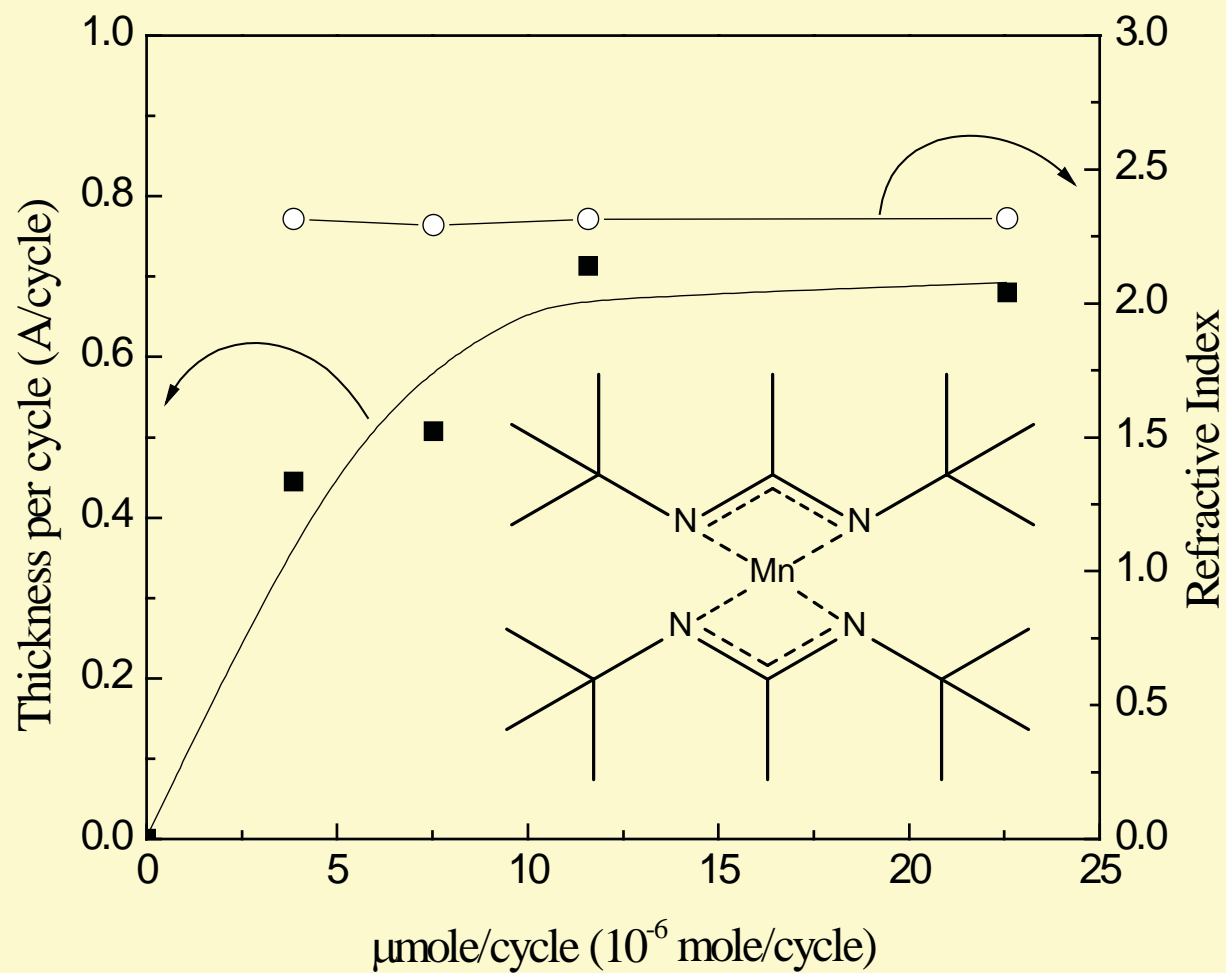
# Saturation Curve for Manganese Oxide

Saturated for doses  $> 10^{-5}$  moles/cycle



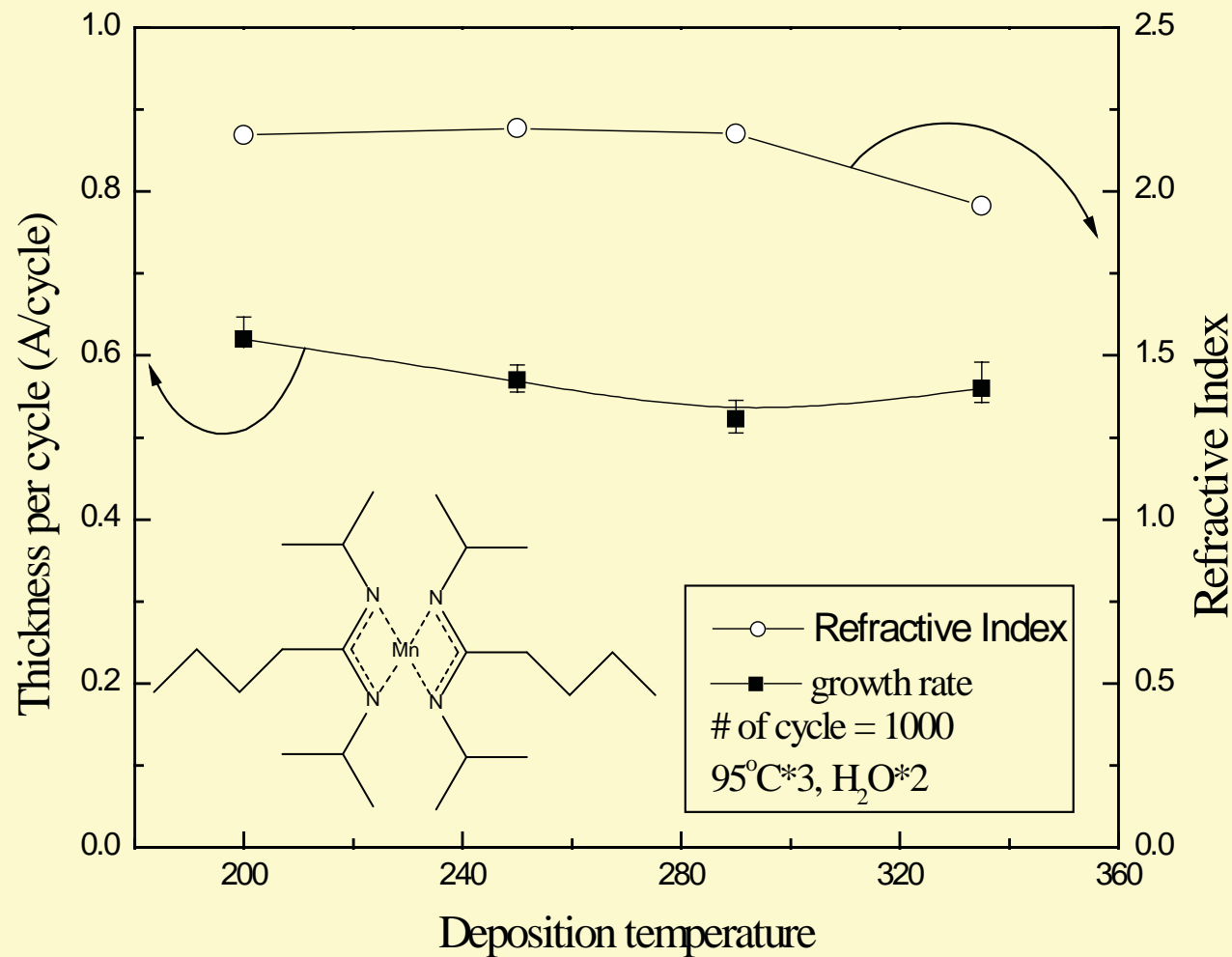
# Saturation Curve for Manganese Oxide

Saturated for doses  $> 10^{-5}$  moles/cycle



# Thickness per Cycle for Manganese Oxide

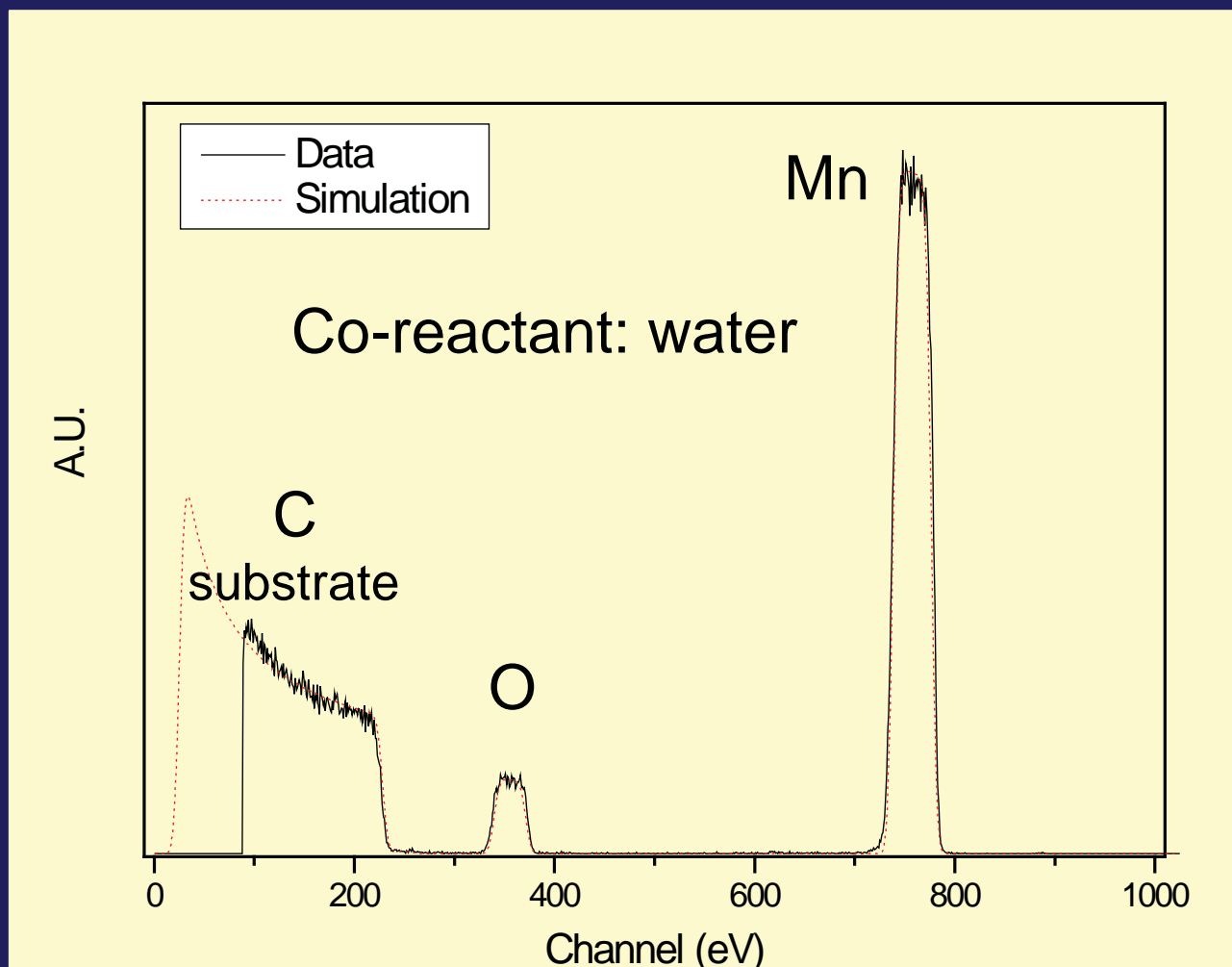
nearly constant from 200 to 340 °C





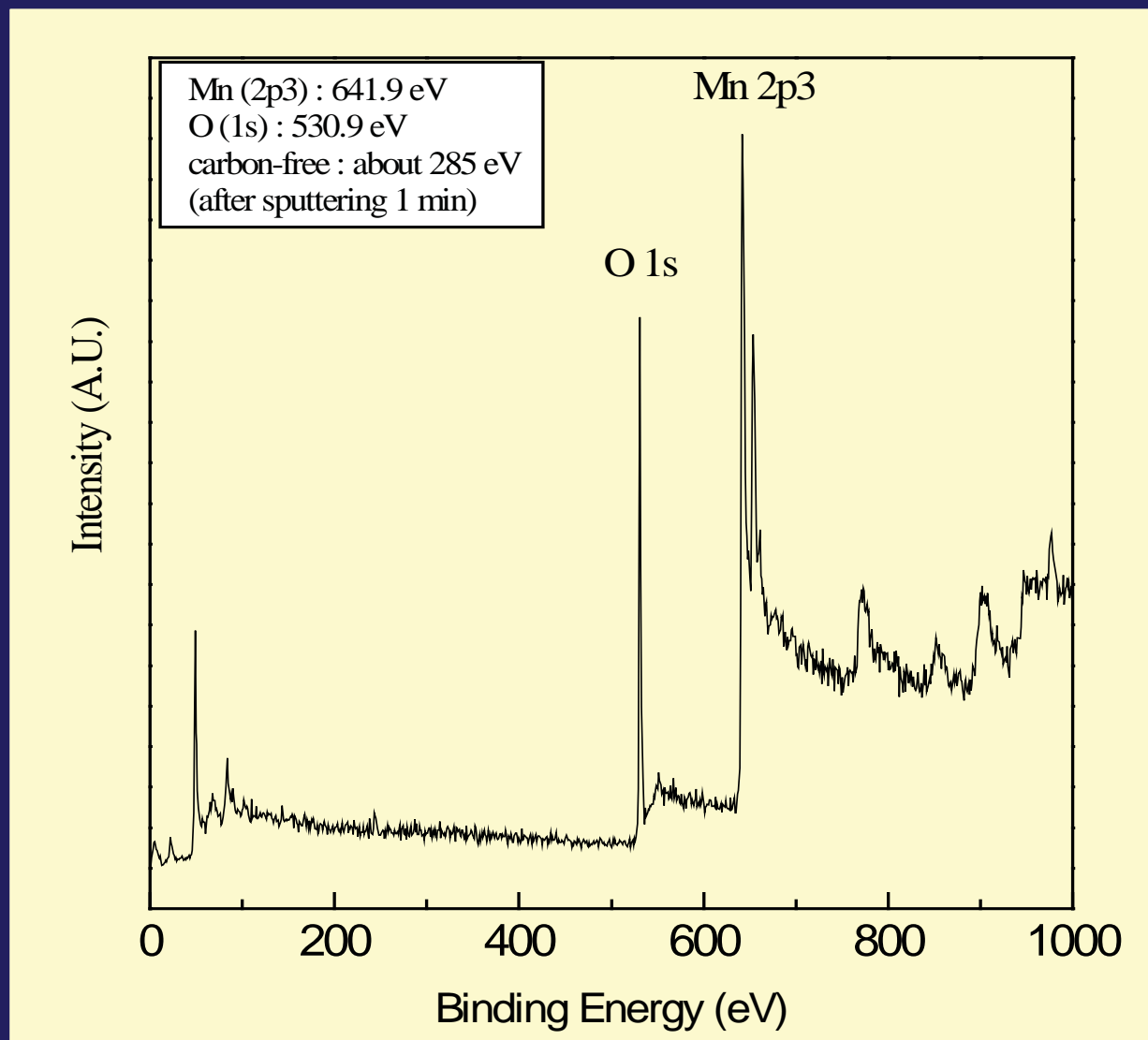
# Rutherford Backscattering Spectroscopy

=> Stoichiometry MnO     Adding O<sub>2</sub> cycles => MnO<sub>2</sub>

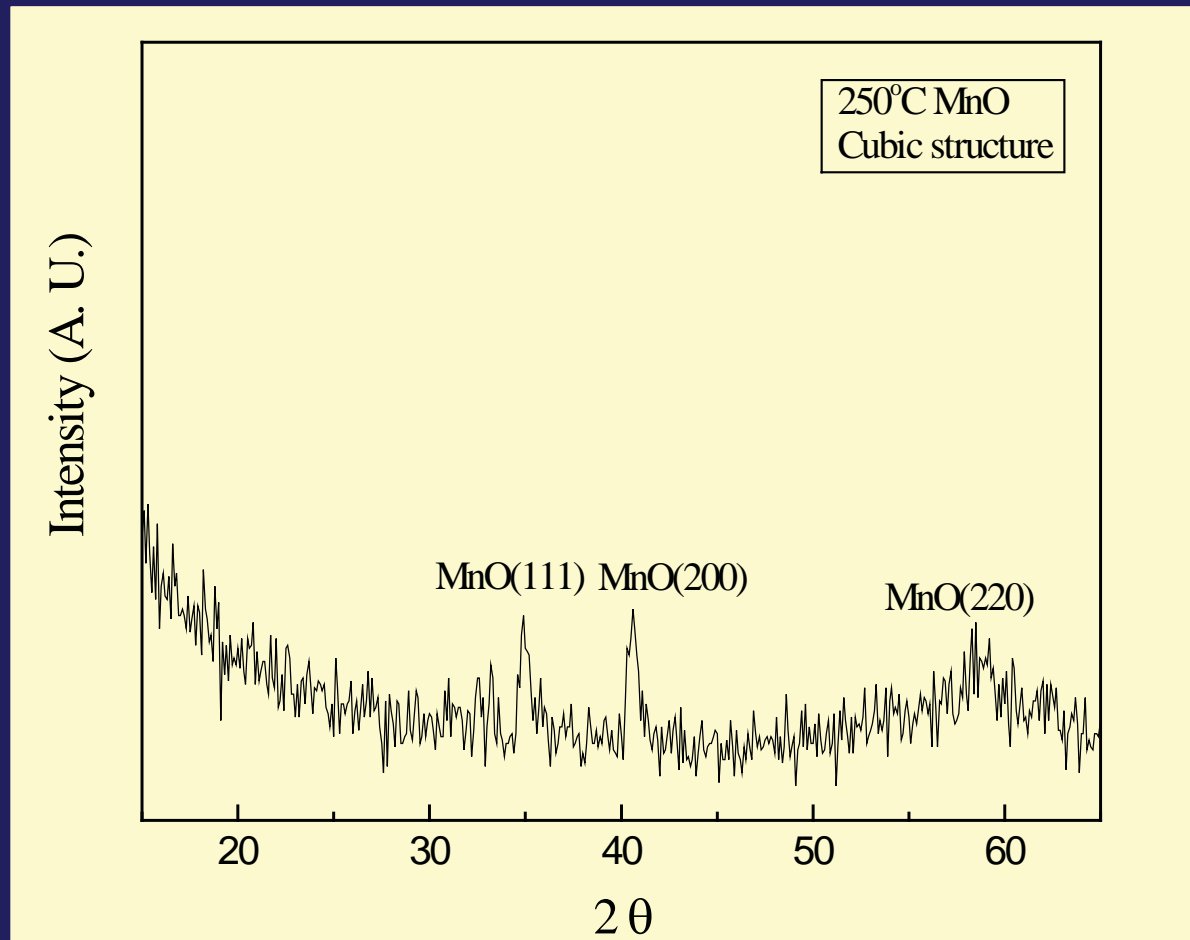


# X-Ray Photoelectron Spectroscopy

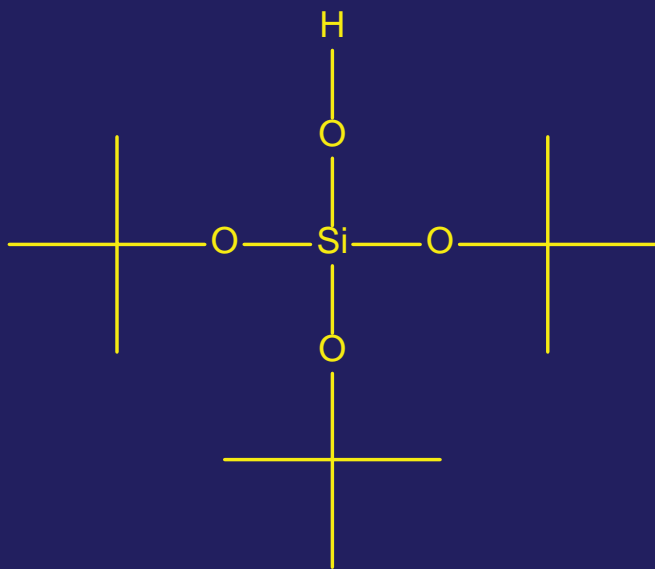
< 1% C or N impurities



# XRD shows polycrystalline MnO

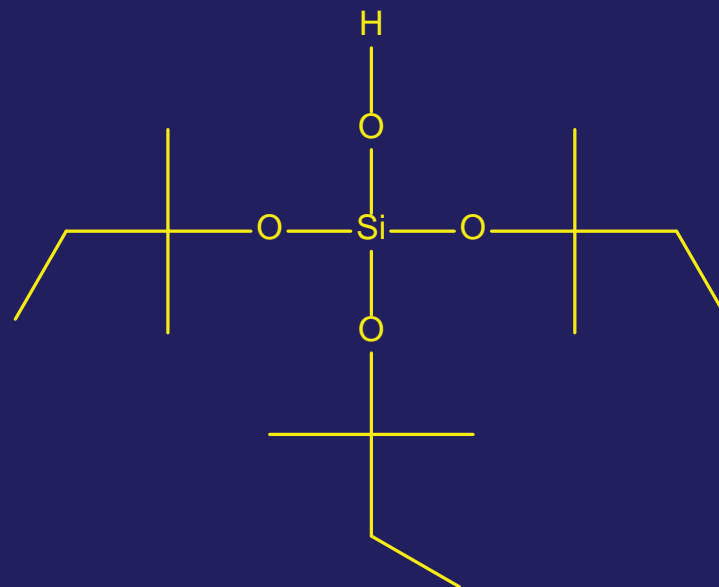


# Precursors for Silicon and Oxygen



tris-*tert*-butoxysilanol (TBS)

melting point: 63 - 65 °C  
boiling point: 205 - 210 °C/ 760 torr



tris-*tert*-pentoxysilanol (TPS)

melting point: < 20 °C  
boiling point: 96-99 °C/ 2-3 torr

# ALD Conditions for Manganese Silicate

Substrate:  $\text{SiO}_2/\text{Si}$

UV ozone cleaning: 2 min

Drying at  $350^\circ\text{C}$ : 1 hour

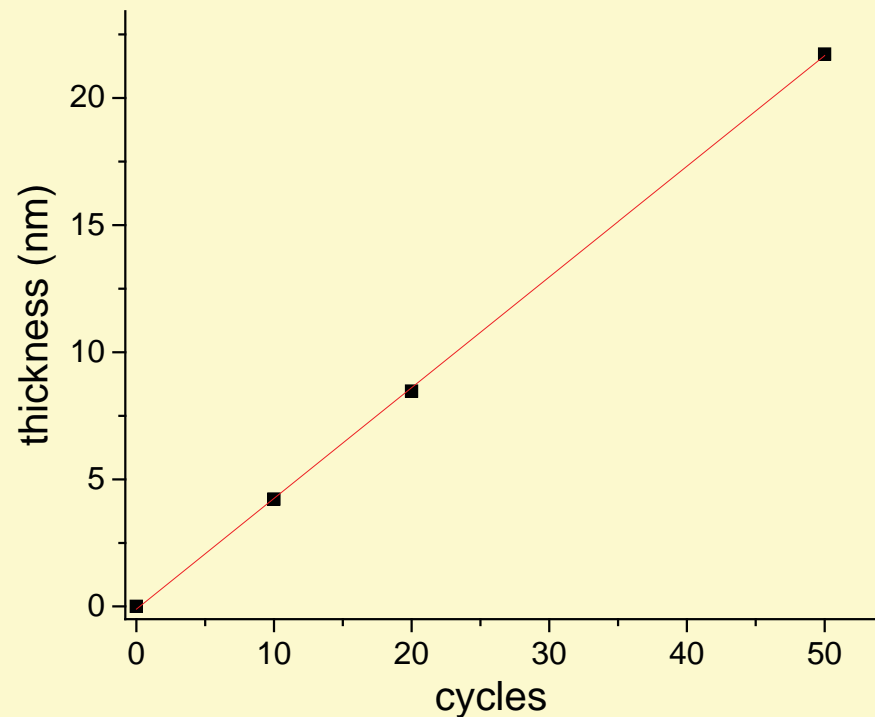
Mn amidinate source =  $105^\circ\text{C}$

Si/O source (TPS) =  $120^\circ\text{C}$

$T(\text{substrate}) = 350^\circ\text{C}$

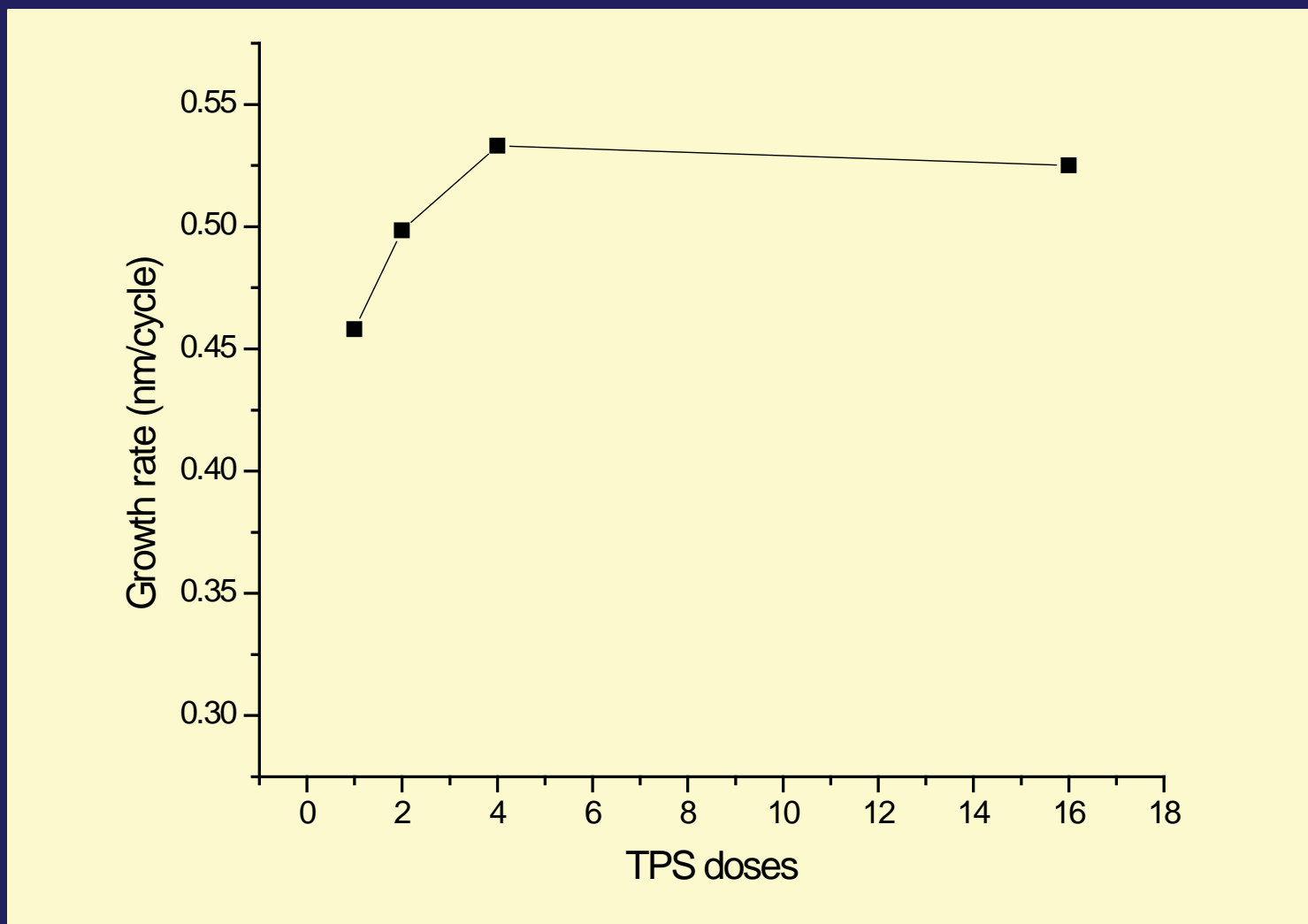
Cycle times (s): 1/30/4/30  
(Mn(amd)/purge/TPS/purge)

growth per cycle = 0.43 nm

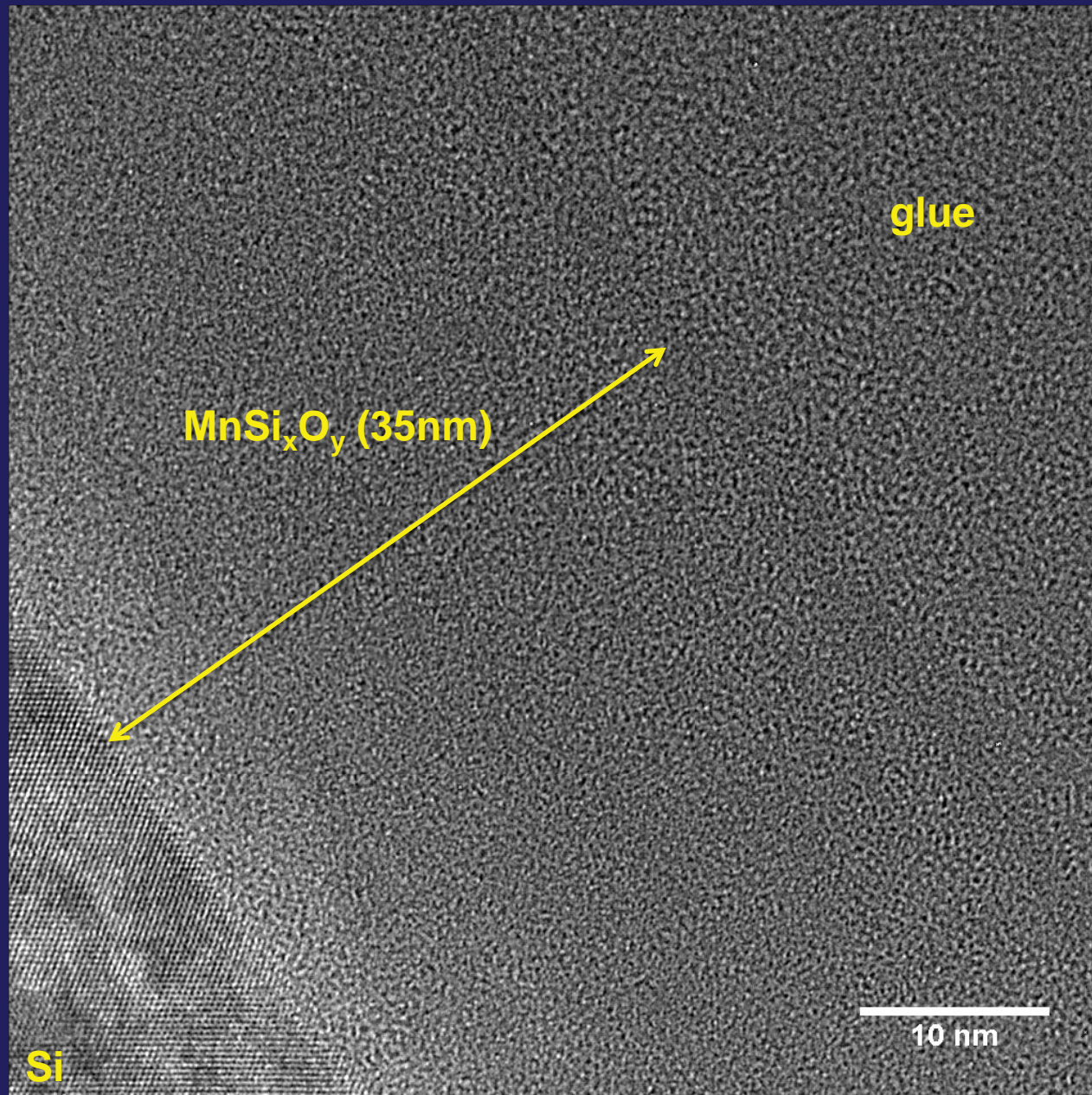


High growth per cycle due to a catalytic mechanism similar to that of aluminum-catalyzed silica: Dennis Hausmann, Jill Becker, Shenglong Wang, Roy G. Gordon, Science 298, 402 (2002)

# Saturation Curve for $\text{MnSi}_x\text{O}_y$ vs. Silicate Precursor

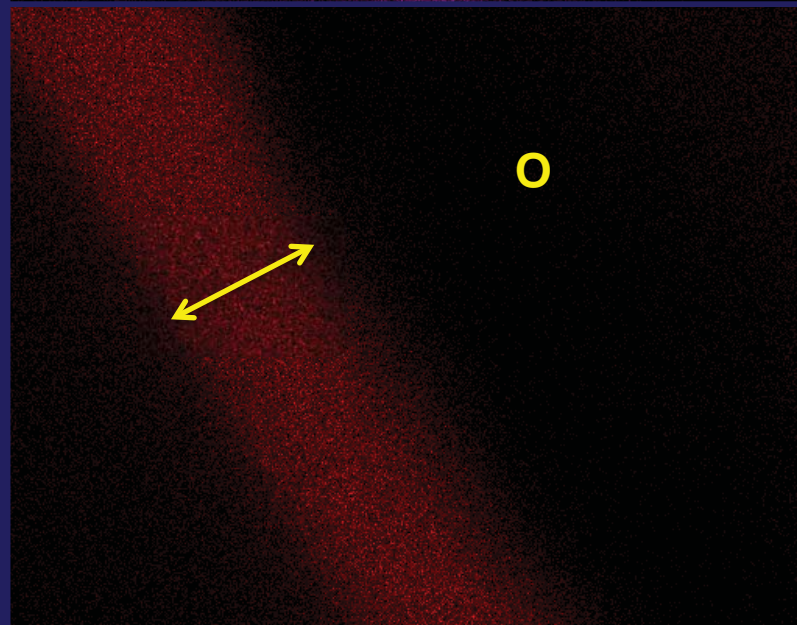
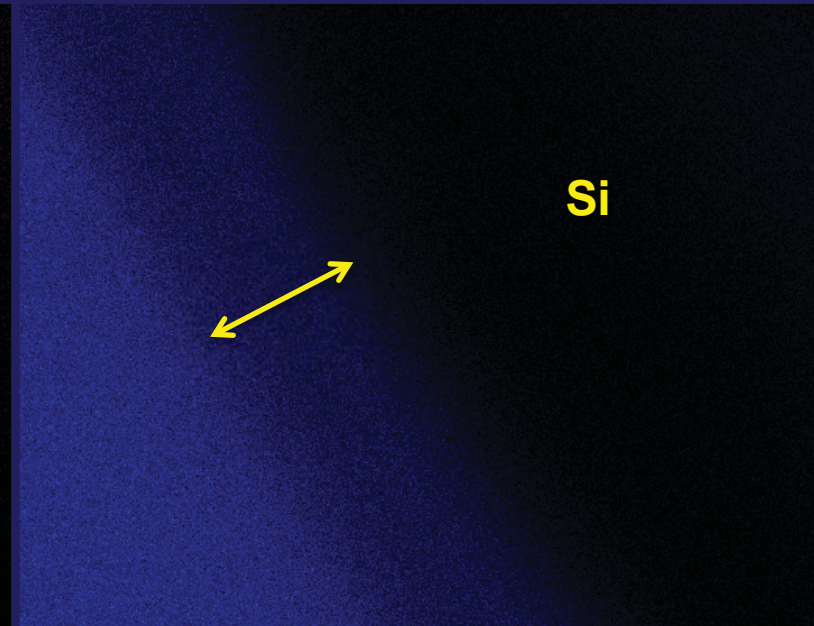
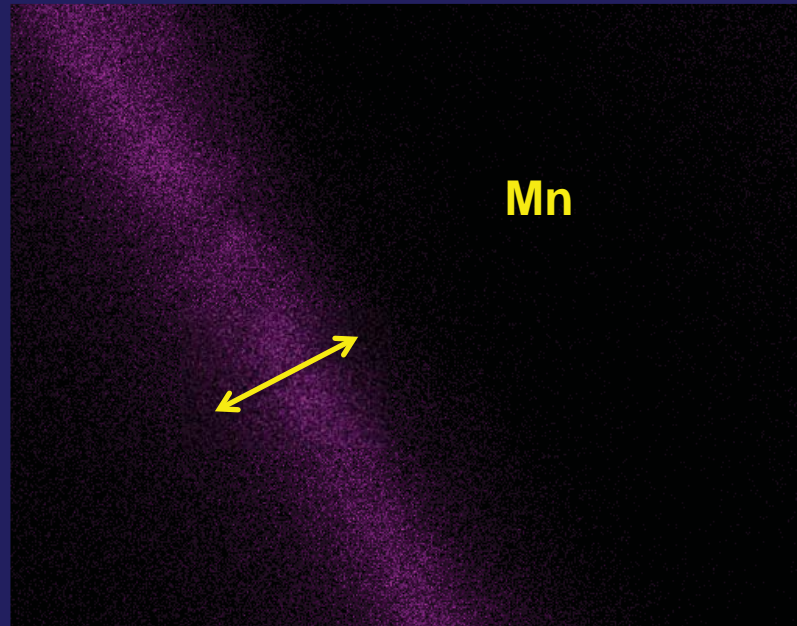


# TEM => Amorphous Structure





# STEM EDX Mapping of Elements





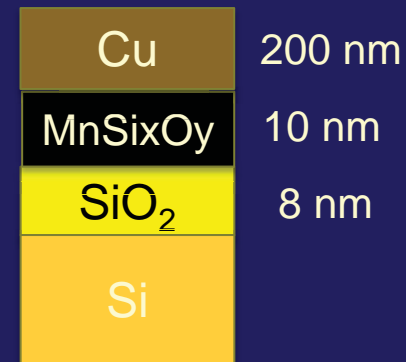
# Composition by Rutherford Backscattering Spectroscopy

Cycles	Mn $10^{15}\text{at/cm}^2$	Si $10^{15}\text{at/cm}^2$	O $10^{15}\text{at/cm}^2$	Mn:Si:O
10	2.32	6.2	24	1 : 2.7 : 10
20	5.56	15	47	1 : 2.7 : 8
50	15.4	41	117	1 : 2.7 : 7.6

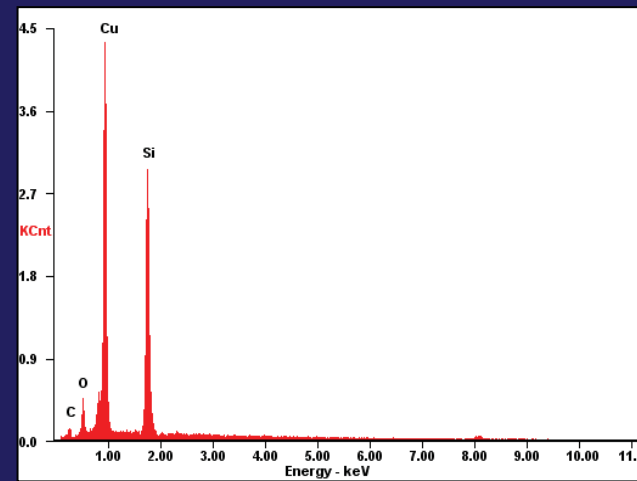
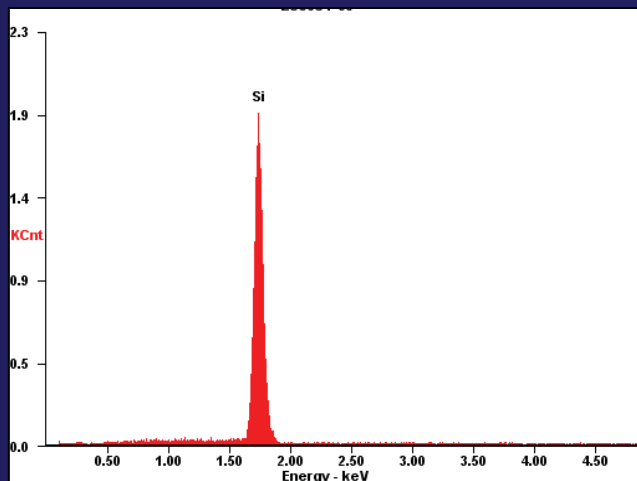
Stoichiometry  $\sim \text{MnSi}_{2.7}\text{O}_{7.6}$  so Mn is oxidized to  $\text{Mn}^{4+}$

# Cu diffusion test

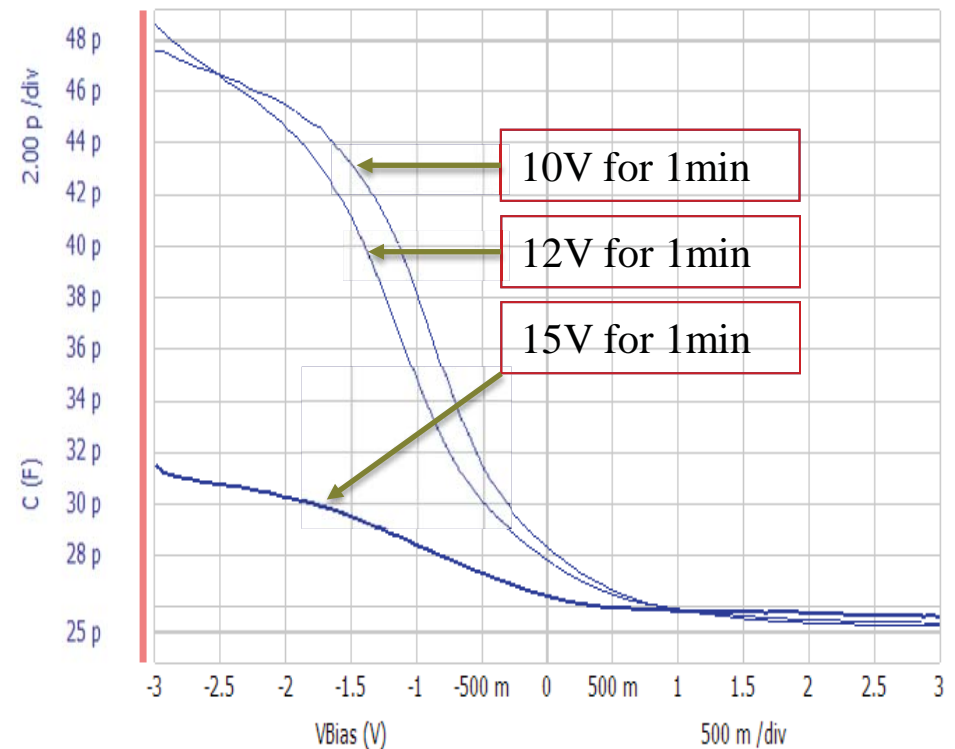
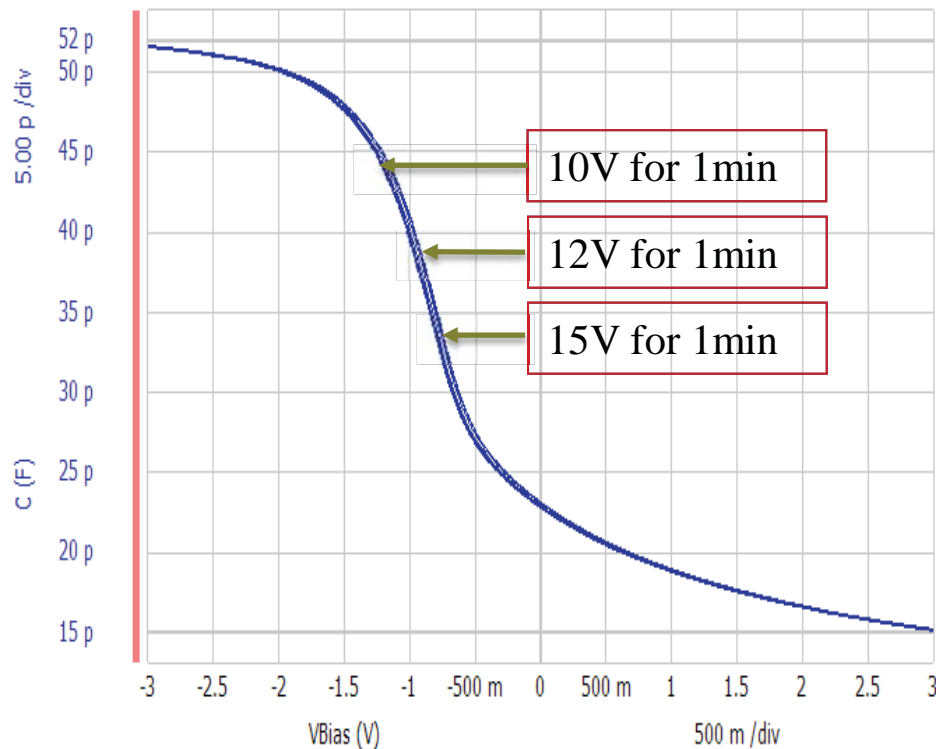
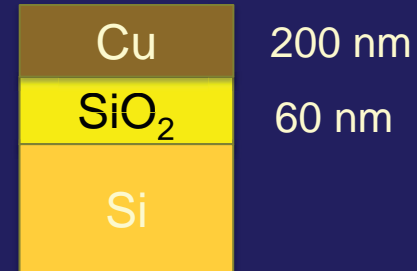
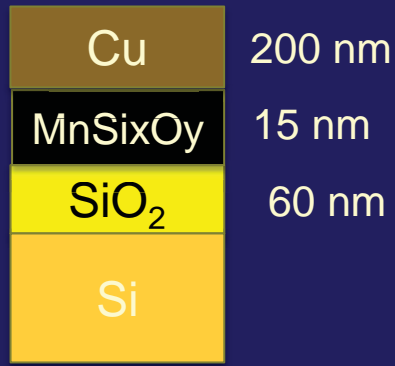
anneal samples in  $N_2$  for 1h at 450 C, use Ni etchant to remove Cu film, then EDX



visible appearance



# CV tests after electric field at room temperature



# Effectiveness of $\text{MnSi}_x\text{O}_y$ as a Cu Diffusion Barrier

Composition	Structure	Cu Barrier	Diffusion Pathway
$\text{SiO}_2$	amorphous	no	open tetrahedral network
$\text{MnSi}_{2.7}\text{O}_{7.6}$	amorphous	yes	paths blocked by Mn ions
$\text{MnO}$	polycrystalline	no	grain boundaries

# Acknowledgements

Precursors supplied by Dow Chemical, Sigma-Aldrich and Strem Chemical

The work was supported as part of the Center for the Next Generation of Materials by Design, an Energy Frontier Research Center funded by the U.S. Department of Energy, Office of Science

Facilities at Harvard's Center for Nanoscale Systems (CNS), a member of the National Nanotechnology Infrastructure Network (NNIN), previously supported by the U. S. National Science Foundation

